

M.M. 808

For cold mounting metallographic samples under pressure

M.M.808 creates a pressurized environment for polymerization to avoid bubbles in the mount without affecting the physical characteristics of the resin.

While M.M.808 can be used with all cold mounting resins, it is highly recommended to be used with transparent EPOXY RESINS 603 / 603.2 and ACRYLIC RESIN 609.

Advantage

By avoiding entrapped bubbles in transparent mounts, the visibility of the sample can be improved.

In all cold mounting resins, avoiding bubbles improve edge retention while grinding and polishing metallographic samples.

By avoiding entrapment of abrasives in bubbles, MM808 helps improve the polishing quality after mounting.

Additionally, using the M.M.808 unit for cold mounting eliminates the odors typical of cold mounting resins.



NEW



Capacity of the pressure pot

Embedding mold Ø 25 mm	30 pcs
Embedding mold Ø 30 mm	24 pcs
Embedding mold Ø 40 mm	15 pcs
Embedding mold Ø 50 mm	10 pcs

Technical Data

Pressure connection	3 to 10 bar
Nominal pressure	2 bar
Max. operating pressure	2,8 bar
Height	300 mm
Width	305 mm
Depth	400 mm
Weight	8,6 kg
Inner diameter of lid opening	210 mm
Inner diameter base	225 mm
Pressure pot height to cover edge	190 mm

Designation	Scope of delivery	Ref.
M.M.808	M.M.808 pressure polymerization device, Quartz timer, Operating manual, Nozzle	08 00808 20

LAM PLAN offers a whole range of molds for cold mounting with M.M.808.



Recommended times for LAM PLAN mounting resins:

Polymerization time

Resin 603	1 h polymerization - (hardening 10 h)
Resin 603.2	20 min. polymerization - (hardening 2 h)
Resin 605	5 - 7 min.
Resin 607	16 - 20 min.
Resin 665	8 - 10 min.
Resin 609	9- 13 min.